



PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

August 8, 2007

Applicants: Uwe HOFMANN et al

Title: LEAD-FREE COPPER ALLOY AND A METHOD OF MANUFACTURE

Serial No.: 10/786 470 Group: 1742

Confirmation No.: 9330

Filed: February 25, 2004

Examiner: Ip

Atty. Docket No.: 5200.P0062US

Examiner: Ip

Mail Stop Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Siri

Herewith is an amendment in the above-identified application.

[] Applicant claims small entity status. See 37 CFR 1.27.

[] The additional filing fee has been calculated as shown below:

	No.	No.	(X)	RATE	()	
For	Filed	Extra	LG Entity	SM Entity	Fee	
Total Claims	(18 - 20 = 0)		x \$ 50.00	x \$ 25.00		
Indep. Claims	(1 - 3 = 0)		x \$200.00	x \$100.00		
[] Multiple Dep. Claim			+ \$360.00	+ \$180.00		
* * * TOTAL FILING FEE * * *						\$ 0.00

- [X] Pursuant to 37 CFR 1.136(a), please extend the shortened period for response by one month. The extension fee is: \$120.00.
- [X] A Check for \$120.00 is enclosed to cover fees.
- [X] Please credit any overpayment, or charge any additional filing fee required under 37 CFR 1.16 or 1.17 by this communication, to Deposit Account No. 06-1382. A duplicate copy of this sheet is enclosed.

IN DUPLICATE

TFC/smd

~~Terryence F. Chapman Reg. No. 32 549~~

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in the envelope addressed to: Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450, on August 8, 2007. 120.00 OP

130.12/04

~~Terryence F. Chapman~~